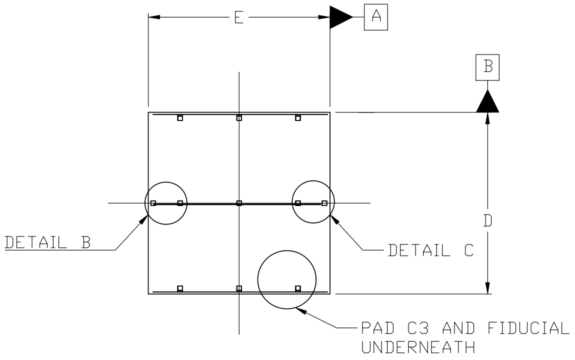
ODCSP8 3.16x3.16x0.64
CASE 570CS
ISSUE A

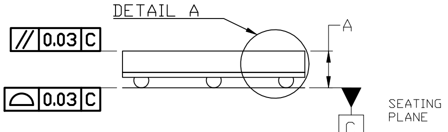
DATE 07 MAY 2019



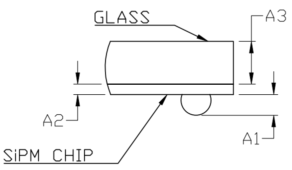
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. ORIENTATION FIDUCIAL LOCATION. LOCATED BETWEEN PADS C2 AND C3.
7. REFERENCE ONLY, NO ACTUAL ORIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.

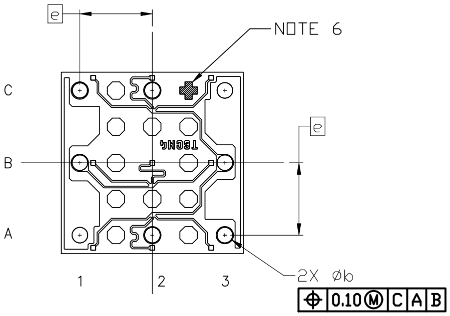


SIDE VIEW

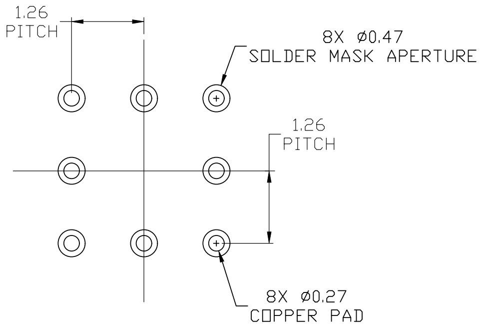


DETAIL A

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.59	0.64	0.69
A1	0.15	0.18	0.20
A2	0.075	0.090	0.105
A3	0.355	0.370	0.385
b	0.23	0.26	0.29
D	3.11	3.16	3.21
E	3.11	3.16	3.21
e	1.26 BSC		

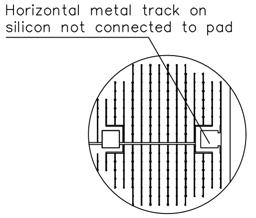


BOTTOM VIEW

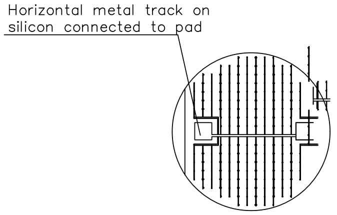


RECOMMENDED MOUNTING FOOTPRINT*
NSMD TYPE

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



DETAIL C
ORIENTATION DETAIL VIEW



DETAIL B
ORIENTATION DETAIL VIEW

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DESCRIPTION:	**ODCSP8 3.16x3.16x0.64**	**PAGE 1 OF 1**